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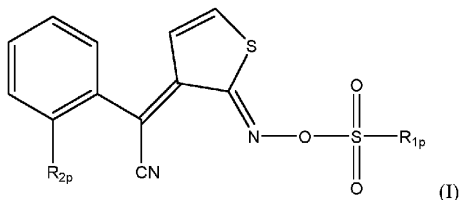
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(54) Title: POST-EXPOSURE BAKE LESS CHEMICALLY AMPLIFIED PHOTORESIST COMPOSITION



(I)

(57) Abstract: Chemically amplified (CA) positive resist compositions are described which are comprised of the following solid components: Component (1) a PAG having structure (I); Component (2) a hydroxybenzoic acid having structure (II); Component (3) a trialkyl amine quencher having structure (III); Component (4) an adhesion promoter which is an aryl-1H-tetrazole-5-thiol derivative having structure (IV); Component (5) a polymer comprising a reaction product formed by reacting without acid catalyst, (i) a Novolak; (ii) a polymer comprising hydroxystyrene and methacrylate and/or methacrylate protected by a high activation energy acid labile group, and a vinyl ether or a heteroalicyclic; Component (6) a polymer comprising structure (V); and Component (7) a Novolak polymer. Also described, is the use of these resist composition in a method for forming a photoresist relief image on a substrate.

WO 2025/132182 A2